

Docket No. 55855-DIV (71987)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: T. Ho et al.
U.S. SERIAL NO.: 10/719,912 GROUP: 2822
FILED: November 21, 2003 EXAMINER: K. Duong
FOR: METHOD OF FABRICATING A THERMALLY ENHANCED WAFER-
LEVEL CHIP SCALE PACKAGE

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CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted by facsimile to the U.S. Patent & Trademark Office by facsimile number 571-273-8300 on January 30, 2007.

By: 
Steven M. Jensen

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT

Applicants are in receipt of the Office Action dated October 30, 2006 of the above-referenced application. A Request for Continued Examination (RCE) is submitted herewith. Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.